# BSP16T1G

# **High Voltage Transistors**

# **PNP Silicon**

## Features

• These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

## MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	V <sub>CEO</sub>	-300	Vdc
Collector-Base Voltage	V <sub>CBO</sub>	-350	Vdc
Emitter-Base Voltage	$V_{\text{EBO}}$	-6.0	Vdc
Collector Current	Ι <sub>C</sub>	-100	mAdc
Total Device Dissipation @ T <sub>A</sub> = 25°C (Note 1)	P <sub>D</sub>	1.5	W
Storage Temperature Range	P <sub>D</sub>	-65 to +150	°C
Junction Temperature	TJ	150	°C

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Мах	Unit
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	83.3	°C/W

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

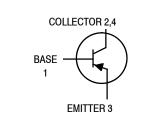
1. Device mounted on a glass epoxy printed circuit board 1.575 in x 1.575 in x 0.059 in; mounting pad for the collector lead min. 0.93 sq. in.

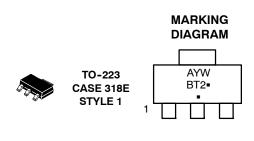


## **ON Semiconductor®**

http://onsemi.com

# PNP SILICON HIGH VOLTAGE TRANSISTOR SURFACE MOUNT





А	= Assembly Location
Y	= Year
W	= Work Week
BT2	=Device Code
-	= Pb-Free Package
(Note: Microc	lot may be in either location)

## ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>
BSP16T1G	TO-223 (Pb-Free)	1000/Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

## BSP16T1G

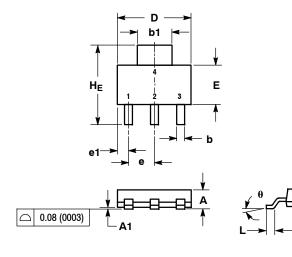
## **ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Collector – Emitter Breakdown Voltage ( $I_C = -50 \text{ mAdc}, I_B = 0, L = 25 \text{ mH}$ )	V <sub>(BR)CEO</sub>	-300	-	Vdc
Collector – Base Breakdown Voltage $(I_{C} = -100 \ \mu Adc, I_{E} = 0)$	V <sub>(BR)CBO</sub>	-300	-	Vdc
Collector-Emitter Cutoff Current ( $V_{CE} = -250 \text{ Vdc}, I_B = 0$ )	I <sub>CES</sub>	-	-50	μAdc
Collector-Base Cutoff Current ( $V_{CB} = -280$ Vdc, $I_E = 0$ )	I <sub>CBO</sub>	-	-1.0	μAdc
Emitter-Base Cutoff Current ( $V_{EB} = -6.0 \text{ Vdc}, I_{C} = 0$ )	I <sub>EBO</sub>	-	-20	μAdc
ON CHARACTERISTICS		*	•	•
DC Current Gain (V <sub>CE</sub> = - 10 Vdc, I <sub>C</sub> = -50 mAdc)	h <sub>FE</sub>	30	120	-
Collector-Emitter Saturation Voltage $(I_{C} = -50 \text{ mAdc}, I_{B} = -5.0 \text{ mAdc})$	V <sub>CE(sat)</sub>	-	- 2.0	Vdc
DYNAMIC CHARACTERISTICS	-	-	-	-
Current Gain – Bandwidth Product (V <sub>CE</sub> = -10 Vdc, I <sub>C</sub> = -10 mAdc, f = 30 MHz)	f <sub>T</sub>	15	-	MHz
Collector-Base Capacitance (V <sub>CB</sub> = -10 Vdc, I <sub>E</sub> = 0, f = 1.0 MHz)	C <sub>obo</sub>	-	15	pF

## BSP16T1G

#### PACKAGE DIMENSIONS

SOT-223 (TO-261) CASE 318E-04 **ISSUE N** 



1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. CONTROLLING DIMENSION: INCH.

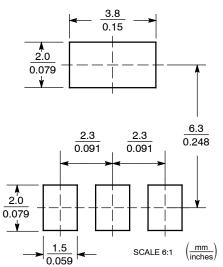
	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	1.50	1.63	1.75	0.060	0.064	0.068
A1	0.02	0.06	0.10	0.001	0.002	0.004
b	0.60	0.75	0.89	0.024	0.030	0.035
b1	2.90	3.06	3.20	0.115	0.121	0.126
c	0.24	0.29	0.35	0.009	0.012	0.014
D	6.30	6.50	6.70	0.249	0.256	0.263
E	3.30	3.50	3.70	0.130	0.138	0.145
е	2.20	2.30	2.40	0.087	0.091	0.094
e1	0.85	0.94	1.05	0.033	0.037	0.041
L	0.20			0.008		
L1	1.50	1.75	2.00	0.060	0.069	0.078
HE	6.70	7.00	7.30	0.264	0.276	0.287
θ	0°	-	10°	0°	-	10°

STYLE 1: PIN 1. BASE 2. COLLE COLLECTOR 3. EMITTER COLLECTOR

NOTES

2.

#### **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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